

3-phase bridge rectifier

SKiiP 39AN22V1

Features*

- NEW SKR PEP diode-technology for enhanced power and environmental robustness
- Highly reliable spring contacts for electrical connections
- UL recognized: File no. E63532

Remarks

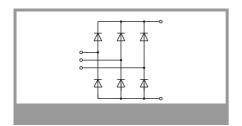
- Max. case temperature limited to T_C=125°C
- Product reliability results valid for T_j≤150°C (recommended T_{j,op}=-40...+150°C)
- MiniSKiiP "Technical Explanations" and "Mounting Instructions" are part of the data sheet. Please refer to both documents for further information.
- For storage and case temperature with TIM see document: "Technical Explanations Thermal Interface Materials"

Absolute Maximum Ratings									
Symbol	Conditions		Values	Unit					
Diode 1									
V_{RRM}	T _j = 25 °C		2200	V					
l _F	λ _{paste} =0.8 W/(mK)	T _s = 25 °C	323	Α					
	T _j = 150 °C	T _s = 70 °C	229	Α					
l _F	λ _{paste} =2.5 W/(mK)	T _s = 25 °C	411	Α					
	T _j = 150 °C	T _s = 70 °C	296	Α					
I _{FSM}	10 ms, sin 180°, T _j	= 150 °C	2000	Α					
i ² t	10 ms, sin 180°, T _j	= 150 °C	20000	A ² s					
Tj			-40 150	°C					

Absolute Maximum Ratings									
Symbol Conditions Values U									
Module									
I _{t(RMS)}	20 A per spring	200	Α						
T _{stg}	module without TIM	-40 125	°C						
V _{isol}	AC sinus 50 Hz, t = 1 min	2500	V						

Characteristics								
Symbol	Conditions		min.	typ.	max.	Unit		
Diode 1	•							
V_{F}	I _F = 149 A	T _j = 25 °C		1.00	1.10	V		
	V _{GE} = 0 V chiplevel	T _j = 125 °C		0.91	1.01	V		
V_{F0}	chiplevel	T _j = 25 °C		0.90	0.97	V		
	Criipievei	T _j = 125 °C		0.78	0.83	V		
r _F	chiplevel	T _j = 25 °C		0.67	0.91	mΩ		
		T _j = 125 °C		0.87	1.18	mΩ		
I _R	T _j = 150 °C, V _F	RRM			9	mA		
R _{th(j-s)}	per Diode, λ _{pa}		0.32		K/W			
R _{th(j-s)}	per Diode, λ _{pa}	ste=2.5 W/(mK)		0.23		K/W		

Characteristics								
Symbol	Conditions	min.	typ.	max.	Unit			
Module								
Ms	to heat sink	2		2.5	Nm			
W	weight		82		g			



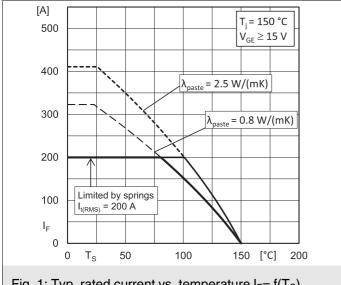


Fig. 1: Typ. rated current vs. temperature $I_F = f(T_S)$

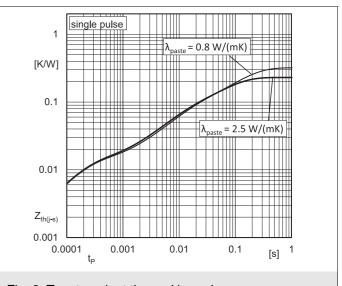


Fig. 2: Typ. transient thermal impedance

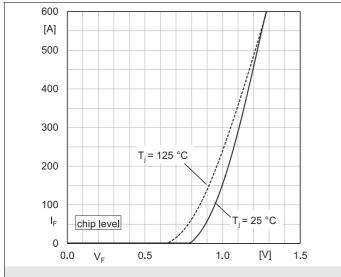
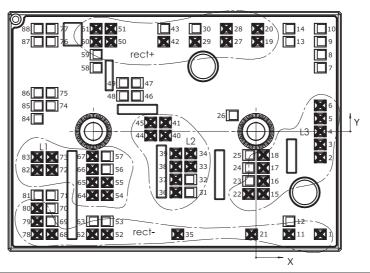


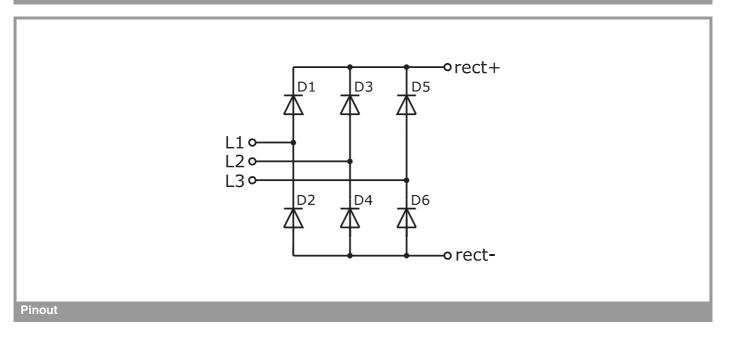
Fig. 3: Typ. input bridge forward characteristic

Pin out											
Pin	X	Y	Function	Pin	X	Y	Function	Pin	X	Y	Function
1	15,83	-25,30	rect-	31	-16,05	-15,02		61	-39,33	25,30	rect+
2	15,83	-6,40	L3	32	-16,05	-11,82		62	-40,23	-25,30	rect-
3	15,83	-3,20	L3	33	-16,05	-8,62	L2	63	-40,23	-22,10	
4	15,83	0	L3	34	-16,05	-5,42	L2	64	-40,23	-15,70	L1
5	15,83	3,20	L3	35	-19,23	-25,30	rect-	65	-40,23	-12,50	L1
6	15,83	6,40	L3	36	-19,70	-15,02	L2	66	-40,23	-9,30	L1
7	15,83	15,70		37	-19,70	-11,82	L2	67	-40,23	-6,10	L1
8	15,83	18,90		38	-19,70	-8,62	L2	68	-50,18	-25,30	rect-
9	15,83	22,10		39	-19,70	-5,42	L2	69	-50,18	-22,10	
10	15,83	25,30		40	-22,26	-1,00	L2	70	-50,18	-18,90	
11	8,13	-25,30	rect-	41	-22,26	2,20	L2	71	-50,18	-15,70	
12	8,13	-22,10		42	-22,68	22,10	rect+	72	-50,18	-9,50	L1
13	8,13	22,10		43	-22,68	25,30		73	-50,18	-6,30	L1
14	8,13	25,30		44	-25,91	-1,00	L2	74	-50,18	6,30	
15	1,83	-15,39	L3	45	-25,91	2,20	L2	75	-50,18	9,50	
16	1,83	-12,19	L3	46	-29,18	8,74		76	-50,18	22,10	
17	1,83	-8,99	L3	47	-29,18	11,94		77	-50,18	25,30	
18	1,83	-5,79	L3	48	-32,83	8,74		78	-53,83	-25,30	rect-
19	0,43	22,10	rect+	49	-32,83	11,94		79	-53,83	-22,10	rect-
20	0,43	25,30	rect+	50	-35,68	22,10	rect+	80	-53,83	-18,90	rect-
21	-1,08	-25,30	rect-	51	-35,68	25,30	rect+	81	-53,83	-15,70	
22	-1,83	-15,39	L3	52	-36,58	-25,30	rect-	82	-53,83	-9,50	L1
23	-1,83	-12,19		53	-36,58	-22,10		83	-53,83	-6,30	L1
24	-1,83	-8,99		54	-36,58	-15,70	L1	84	-53,83	3,10	
25	-1,83	- 5,79		55	-36,58	-12,50	L1	85	-53,83	6,30	
26	-5,83	3,95		56	-36,58	-9,30		86	-53,83	9,50	
27	- 7,28	22,10	rect+	57	-36,58	-6,10		87	-53,83	22,10	
28	- 7,28	25,30	rect+	58	-39,33	15,70		88	-53,83	25,30	
29	-14,98	22,10	rect+	59	-39,33	18,90					
30	-14,98	25,30		60	-39,33	22,10	rect+				

all values in mm



Pinout and Dimensions



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This is an electrostatic discharge sensitive device (ESDS) due to international standard IEC 61340.

*IMPORTANT INFORMATION AND WARNINGS

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